SMT FLUX GEL

TYPE "MOB39"

SMT Flux Gel Type "MOB39": Specially formulated for Ball Grid Array (BGA) Applications, Soldering & Rework

Flux Gel MOB39 has been specially developed in the laboratories of MBO for use in soldering Surface Mount Technology (SMT) component applications.

Flux Gel MOB39 is primarily intended for micro-electronics circuits using BGA components pre-loaded or bumped with solder pads.

Flux Gel MOB39 can also be used for other soldering applications to include rework and repair where the component terminations are already solder tinned or bumped.

MOB39 is suitable for use in both lead free and leaded applications – one material, two technologies.

Benefits gained from using MOB39 with BGA components over solder cream include:

Usage:

- Good deposition resolution of flux
- Avoids bridging of tracks
- Compatibility with existing materials
- Easy to use
- Minimal residues

Flux Gel MOB39 is manufactured using high purity rosin with the activation level equivalent to that of RMA (Rosin Mildly Active) materials. The soldered connection will be the same as that produced with solder cream which had been applied by screen or stencil deposition.

Flux Gel MOB39 is a "no-clean" product. After soldering, the very low level of residue remaining may be left on the components or circuit without risk of corrosion.

Physiochemical Characteristics:

Appearance	: Gelatinous
Colour	: Transparent Honey
Density	: 1.01
Chlorine rate	: < 0.05%
Non volatile Content	: 70%
Viscosity	: 400 Pas
Flash Point	: 100%

Application Notes:

Spread a thin film of MOB39 onto the circuit in the component placement area or, alternatively, onto the base of the component being soldered. A thickness of 30 – 40 microns is recommended.

- MOB39 remains active for up to 8 hours.
- MOB39 can be left on the circuit 6 hours before placement of the component.
- Soldering should be performed shortly thereafter.

Flux Gel MOB39 is also suitable for use in the repair and rework of solder joints and to prepare the surfaces of circuits for the replacement of components. After de-soldering the component to be

replaced, apply MOB39 to the PCB in a thin layer, position the new component and apply heat locally.

Avoid using excess MOB39.

After fusion the process leaves little or no visible or reactive residues, hence eliminating the need for cleaning and the risk of corrosion.

Health and Safety:

Use in a well-ventilated area away from any source of ignition.
Risk Classification R42/43
Safety Classification S3/7 and S24/25

Packaging:

5cc, 10cc syringes or cartridges, 100g Jars. Other packaging is available on request. Contact MBO.

Storage / Usable life:

May be stored in original containers at ambient temperatures or in a refrigerator at 6°C - 10°C for up to 6 months.

MBO UK – Mill End – Standon – Ware – Herts – SG11 1LR
Email : info@mbouk.co.uk
Website : www.mbouk.co.uk
Tel : +44(0)1920 823 999
Fax : +44(0)1920 823 631